

MITSUBISHI LSIs

M5M5256CP,FP,KP,VP,RV-55LL,-55XL, -70LL,-70XL

262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM

DESCRIPTION

This M5M5256CP,FP,KP,VP,RV is a 262144-bit CMOS static RAMs organized as 32768-words by 8-bits which is fabricated using high-performance 3 polysilicon CMOS technology. The use of resistive load NMOS cells and CMOS periphery result in a high-density and low-power static RAM. Stand-by current is small enough for battery back-up application. It is ideal for the memory systems which require simple interface.

Especially the M5M5256CVP, RV are packaged in a 28-pin thin small outline package. Two types of devices are available, M5M5256CVP (normal lead bend type package) and M5M5256CRV(reverse lead bend type package). Using both type of devices, it becomes very easy to design a printed circuit board.

FEATURES

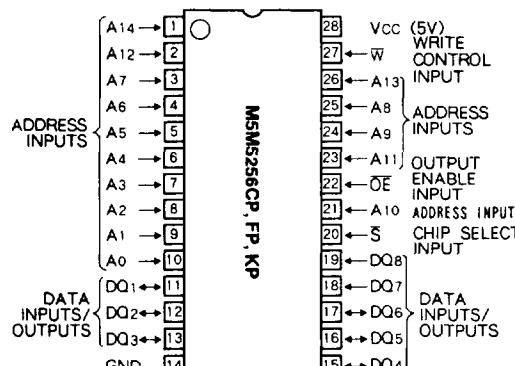
Type name	Access time (max)	Power supply current	
		Active (max)	Stand-by (max)
M5M5256CP,FP,KP,VP,RV-55LL	55ns		20 μ A (Vcc = 5.5V)
M5M5256CP,FP,KP,VP,RV-70LL	70ns	60mA (Vcc=5.5V)	
M5M5256CP,FP,KP,VP,RV-55XL	55ns		5 μ A (Vcc = 5.5V)
M5M5256CP,FP,KP,VP,RV-70XL	70ns		0.05 μ A (Vcc = 3V, typ)

- Single + 5V power supply
- No clocks, no refresh
- Data-hold on + 2V power supply
- Directly TTL compatible : All inputs and outputs
- Three-state outputs : OR-tie capability
- Simple memory expansion by \bar{S}
- \bar{OE} prevents data contention in the I/O bus
- Common data I/O
- Low stand-by current..... 0.05 μ A (typ)
- Package
 - M5M5256CP..... 28 pin 600 mil DIP
 - M5M5256CKP..... 28 pin 300 mil DIP
 - M5M5256CFP..... 28 pin 450 mil SOP
 - M5M5256CVP, RV..... 28pin 8 x 13.4mm² TSOP

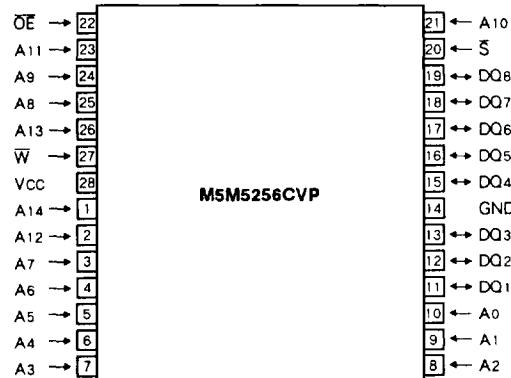
APPLICATION

Small capacity memory units

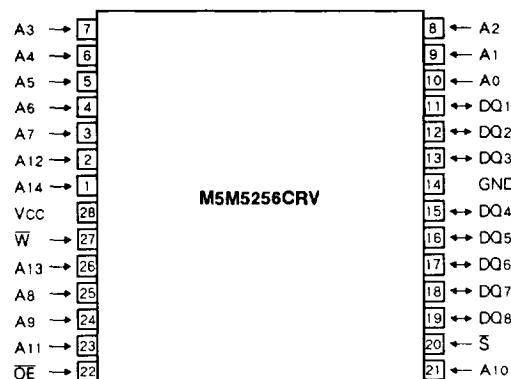
PIN CONFIGURATION (TOP VIEW)



Outline 28P4 (P)
28P2W-C (FP)
28P4Y (KP)



Outline 28P2C-A



Outline 28P2C-B

M5M5256CP,FP,KP,VP,RV-55LL,-55XL,-70LL,-70XL**262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM****FUNCTION**

The operation mode of the M5M5256CP,FP,KP,VP,RV is determined by a combination of the device control inputs \bar{S} , \bar{W} and \bar{OE} . Each mode is summarized in the function table.

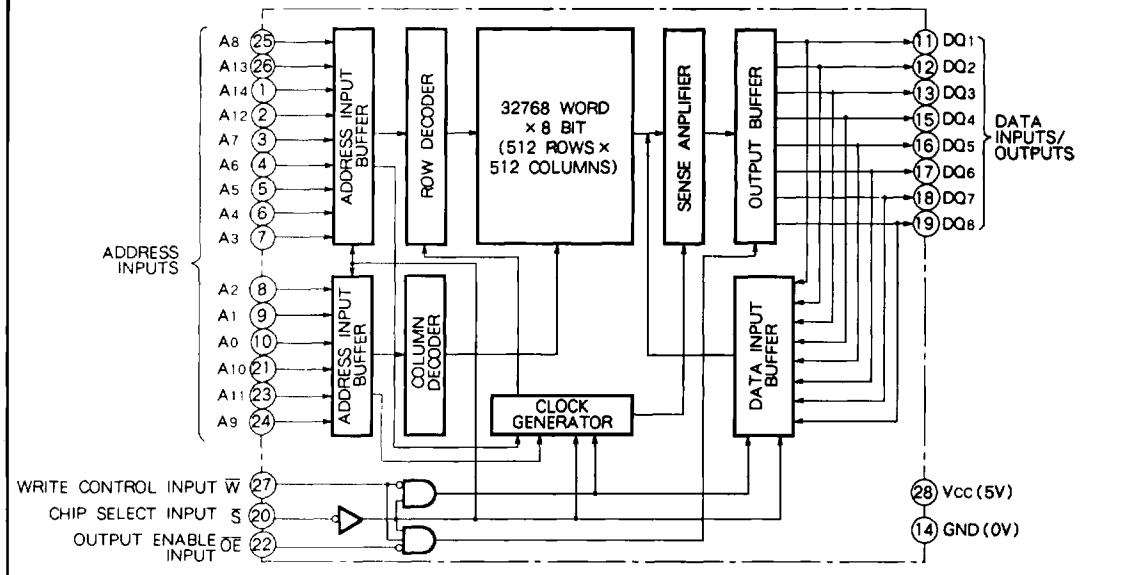
A write cycle is executed whenever the low level \bar{W} overlaps with the low level \bar{S} . The address must be set-up before the write cycle and must be stable during the entire cycle. The data is latched into a cell on the trailing edge of \bar{W} , \bar{S} , whichever occurs first, requiring the set-up and hold time relative to these edge to be maintained. The output enable \bar{OE} directly controls the output stage. Setting the \bar{OE} at a high level, the output stage is in a high-impedance state, and the data bus contention problem in the write cycle is eliminated.

A read cycle is executed by setting \bar{W} at a high level and \bar{OE} at a low level while \bar{S} are in an active state.

When setting \bar{S} at a high level, the chip is in a non-selectable mode in which both reading and writing are disabled. In this mode, the output stage is in a high-impedance state, allowing OR-tie with other chips and memory expansion by \bar{S} . The power supply current is reduced as low as the stand-by current which is specified as I_{CC3} or I_{CC4} , and the memory data can be held +2V power supply, enabling battery back-up operation during power failure or power-down operation in the non-selected mode.

FUNCTION TABLE

\bar{S}	\bar{W}	\bar{OE}	Mode	DQ	I_{CC}
H	X	X	Non selection	High-impedance	Stand-by
L	L	X	Write	Din	Active
L	H	L	Read	Dout	Active
L	H	H		High-impedance	Active

BLOCK DIAGRAM

M5M5256CP,FP,KP,VP,RV-55LL,-55XL,-70LL,-70XL**262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM****ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Conditions	Ratings	Unit
Vcc	Supply voltage	With respect to GND	- 0.3~7	V
Vi	Input voltage		- 0.3*~Vcc + 0.3	V
Vo	Output voltage		0~Vcc	V
Pa	Power dissipation	Ta = 25 °C	700	mW
Topr	Operating temperature		0~70	°C
Tstg	Storage temperature		- 65~150	°C

* - 3.0V in case of AC(Pulse width ≤ 30ns)

DC ELECTRICAL CHARACTERISTICS (Ta = 0~70 °C, Vcc = 5V ± 10 %, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
ViH	High-level input voltage		2.2		Vcc+0.3	V
ViL	Low-level input voltage		- 0.3*		0.8	V
VOH1	High-level output voltage 1	IoH = - 1mA	2.4			V
VOH2	High-level output voltage 2	IoH = - 0.1mA	Vcc-0.5			V
VOl	Low-level output voltage	IoL = 2mA			0.4	V
Ii	Input leakage current	VL = 0~Vcc			± 1	μA
Io	Output leakage current	Si = ViH or OE = ViH, Vi/o = 0~Vcc			± 1	μA
Icc1	Active supply current (AC, MOS level)	Si ≤ 0.2V Other inputs ≤ 0.2V or ≥ Vcc - 0.2V Output open Min.cycle	55ns 70ns	35 30	55 50	mA
Icc2	Active supply current (AC, TTL level)	Si = ViL Other inputs = ViH or ViL Output open Min.cycle	55ns 70ns	40 35	60 55	mA
Icc3	Stand-by supply current	Si ≥ Vcc - 0.2V, Other inputs = 0~Vcc	-LL -XL		20 0.1	μA μA
Icc4	Stand-by supply current	Si = ViH, Other inputs = 0~Vcc			5 3	μA mA

* - 3.0V in case of AC(Pulse width 30ns)

CAPACITANCE (Ta = 0~70 °C, Vcc = 5V ± 10 %, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
Ci	Input capacitance (Ta = 25 °C)	Vi = GND, Vi = 25mVrms, f = 1MHz			6	pF
Co	Output capacitance (Ta = 25 °C)	Vo = GND, Vo = 25mVrms, f = 1MHz			8	pF

Note 1. Direction for current flowing into IC is indicated as positive.(no mark)

2. Typical value is Vcc = 5V, Ta = 25 °C.

3. Ci, Co are periodically sampled and are not 100 % tested.

M5M5256CP,FP,KP,VP,RV-55LL,-55XL,-70LL,-70XL**262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM****AC ELECTRICAL CHARACTERISTICS (Ta = 0~70°C, Vcc = 5V ± 10%, unless otherwise noted)****(1) MEASUREMENT CONDITIONS**Input pulse level $V_{IH} = 2.4V$, $V_{IL} = 0.6V$

Input rise and fall time 5ns

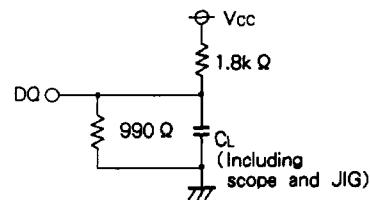
Reference level $V_{OH} = V_{OL} = 1.5V$ Transition is measured $\pm 500mV$ from steady state voltage.(for t_{on} , t_{dis})Output loads Fig.1. $C_L = 50pF$ $C_L = 5pF$ (for t_{on} , t_{dis})

Fig.1 Output load

(2) READ CYCLE

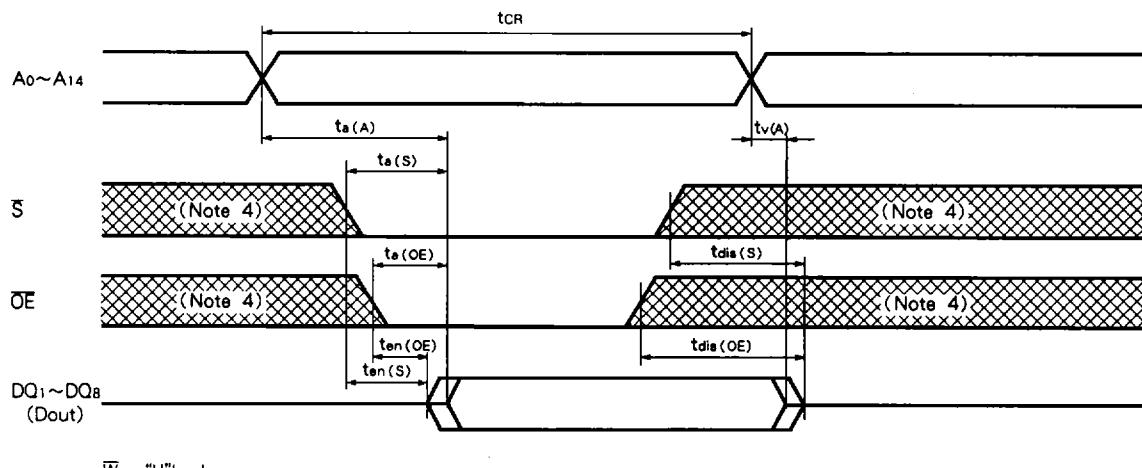
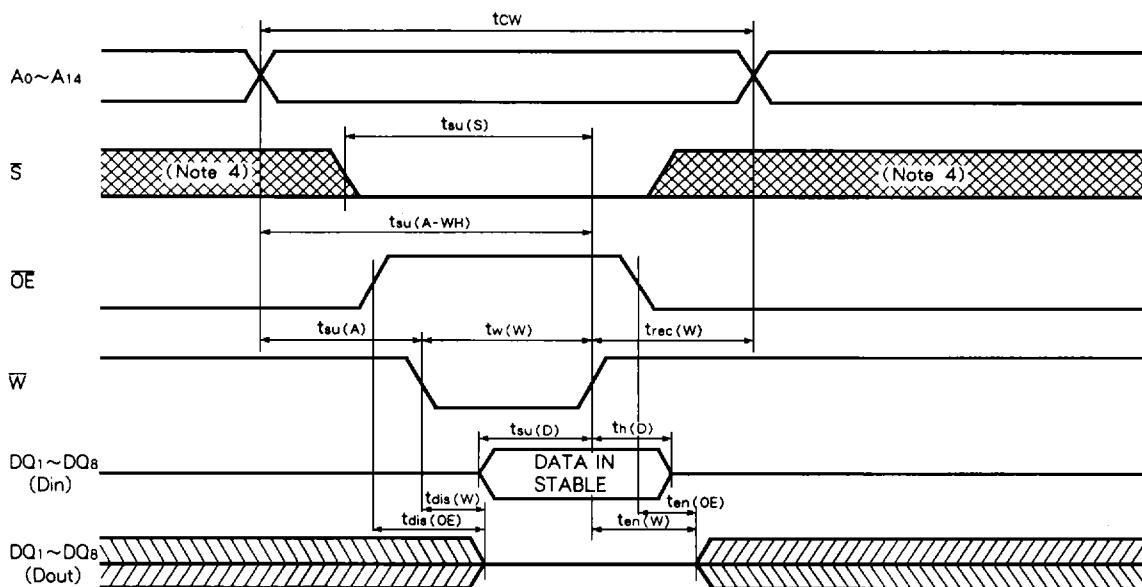
Symbol	Parameter	Limits						Unit	
		M5M5256C-55LL M5M5256C-55XL			M5M5256C-70LL M5M5256C-70XL				
		Min	Typ	Max	Min	Typ	Max		
t_{CR}	Read cycle time	55			70			ns	
$t_{A(A)}$	Address access time			55			70	ns	
$t_{A(S)}$	Chip select access time			55			70	ns	
$t_{OE(OE)}$	Output enable access time			30			35	ns	
$t_{dis(S)}$	Output disable time after S high			20			25	ns	
$t_{dis(OE)}$	Output disable time after OE high			20			25	ns	
$t_{on(S)}$	Output enable time after S low	5			5			ns	
$t_{on(OE)}$	Output enable time after OE low	5			5			ns	
$t_{v(A)}$	Data valid time after address	10			10			ns	

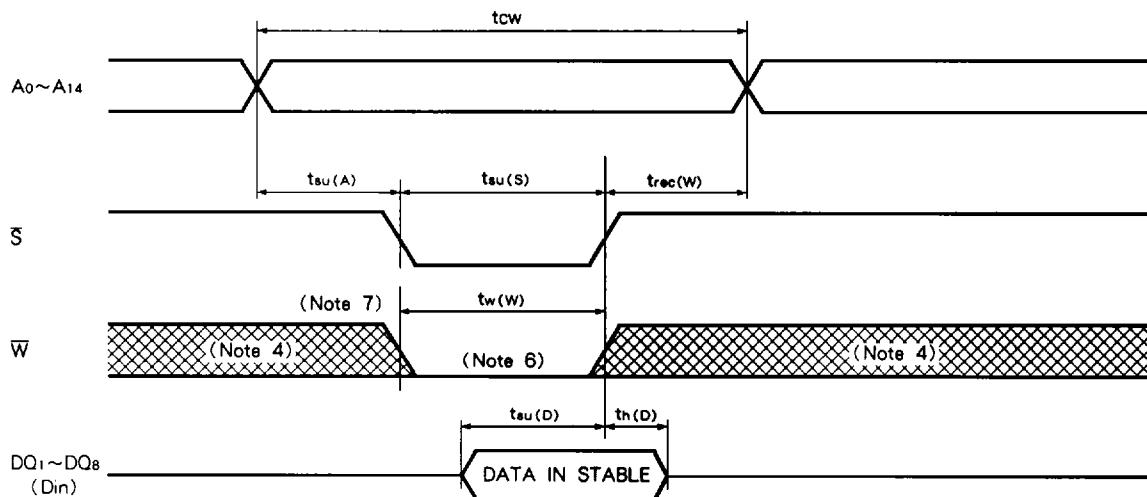
(3) WRITE CYCLE

Symbol	Parameter	Limits						Unit	
		M5M5256C-55LL M5M5256C-55XL			M5M5256C-70LL M5M5256C-70XL				
		Min	Typ	Max	Min	Typ	Max		
t_{CW}	Write cycle time	55			70			ns	
$t_w(W)$	Write pulse width	45			55			ns	
$t_{su(A)}$	Address set up time	0			0			ns	
$t_{su(A-WH)}$	Address set up time with respect to W high	50			65			ns	
$t_{su(S)}$	Chip select set up time	50			65			ns	
$t_{su(D)}$	Data set up time	25			30			ns	
$t_h(D)$	Data hold time	0			0			ns	
$t_{rec(W)}$	Write recovery time	0			0			ns	
$t_{dis(W)}$	Output disable time after W low			20			25	ns	
$t_{dis(OE)}$	Output disable time after OE high			20			25	ns	
$t_{on(W)}$	Output enable time after W high	5			5			ns	
$t_{on(OE)}$	Output enable time after OE low	5			5			ns	

(4) TIMING DIAGRAMS

Read Cycle

Write cycle (\bar{W} control mode)

M5M5256CP,FP,KP,VP,RV-55LL,-55XL,-70LL,-70XL**262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM****Write cycle (\bar{S} control mode)**

Note 4. Hatching indicates the state is don't care.

5. Writing is executed in overlap of \bar{S} and \bar{W} low.6. If \bar{W} goes low simultaneously with or prior to \bar{S} , the output remains in the high-impedance state.

7. Don't apply inverted phase signal externally when DQ pin is in output mode.

8. t_{en}, t_{dis} are periodically sampled and are not 100% tested.

M5M5256CP,FP,KP,VP,RV-55LL,-55XL,-70LL,-70XL**262144-BIT(32768-WORD BY 8-BIT)CMOS STATIC RAM****POWER DOWN CHARACTERISTICS**(1) ELECTRICAL CHARACTERISTICS ($T_a = 0\sim 70^\circ C$, $V_{cc} = 5V \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$V_{CC(PD)}$	Power down supply voltage		2			V
$V_I(S)$	Chip select input S	2.2V $\leq V_{CC(PD)}$	2.2			V
		2V $\leq V_{CC(PD)} \leq 2.2V$			$V_{CC(PD)}$	
$I_{CC(PD)}$	Power down supply current	$V_{cc} = 3V$	-LL		10*	μA
		Other inputs = 3V	-XL	0.05	2**	μA

* $T_a = 25^\circ C$, $I_{CC(PD)} = 1 \mu A$ ** $T_a = 25^\circ C$, $I_{CC(PD)} = 0.2 \mu A$ (2) TIMING REQUIREMENTS ($T_a = 0\sim 70^\circ C$, $V_{cc} = 5V \pm 10\%$, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
$t_{su(PD)}$	Power down set up time		0			ns
$t_{rec(PD)}$	Power down recovery time			t_{CR}		ns

(3) POWER DOWN CHARACTERISTICS

 S control mode